

SMD High Current Molded Inductors - FCH5030- Series

FCH5030-Series

●Features:

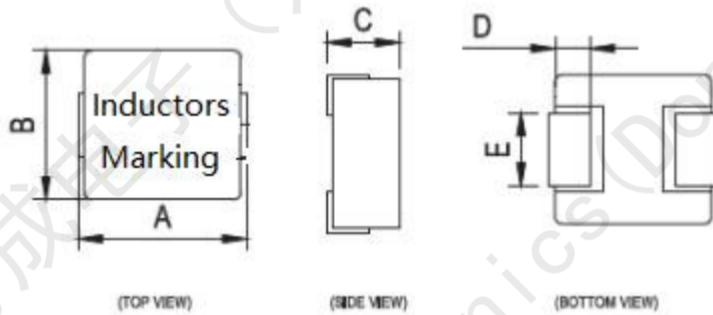
- Ultra low cost
- Shielded constructions
- High current rating up to DC 23Amp
- High frequency range up to 5MHz
- Very low DC resistance
- Low Noise
- RoHS compliant

●Applications:

- PDA/Notebook/Desktop/Server applications
- DC/DC converter

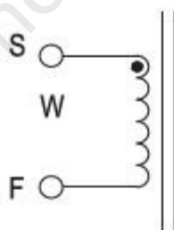


1.Shapes and Dimensions (形状及尺寸)

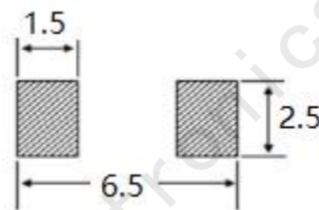


Type	A	B	C	D	E
FCH5030	5.7±0.3	5.2±0.3	3.0 MAX	1.2±0.3	2.3±0.3

2.Schematic:



3.layout recommendation:(mm)



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4. FCH5030 -Series:

Part Number (品名)	Inductance (uH) ±20% (电感值)	DCR(mΩ) (直流阻抗)		Isat DC Current (A) (饱和电流)	Irms DC Current (A) (温升电流)
		Typical	MAX	Typical	Typical
FCH5030-R15M	0.15	2.3	2.7	20.0	23.0
FCH0530-R20M	0.20	3.6	4.3	18.0	17.0
FCH5030-R22M	0.22	3.5	5.5	17.0	16.0
FCH5030-R33M	0.33	6.5	8.0	15.5	15.0
FCH5030-R47M	0.47	6.5	8.5	19.0	13.0
FCH5030-R68M	0.68	11.0	12.0	11.5	9.9
FCH5030-1R0M	1.00	9.6	12.5	9.5	9.0
FCH5030-1R2M	1.20	12.0	16.0	9.0	8.0
FCH5030-1R5M	1.50	15.0	19.0	9.0	7.5
FCH5030-2R2M	2.20	18.7	22.0	7.0	6.5
FCH5030-3R3M	3.30	28.6	33.5	6.0	5.5
FCH5030-4R7M	4.70	45.6	54.0	5.0	4.5
FCH5030-5R6M	5.60	55.0	66.0	4.5	4.0
FCH5030-6R8M	6.80	74.0	86.0	4.0	3.5
FCH5030-8R2M	8.20	95.0	100.0	3.8	3.2
FCH5030-100M	10.00	89.8	104.0	3.5	3.0
FCH5030-150M	15.00	189.0	218.0	3.0	2.5
FCH5030-220M	22.00	298.0	342.0	2.0	1.5
FCH5030-330M	33.00	310.0	341.0	1.6	1.3
FCH5030-470M	47.00	379.0	436.0	1.6	1.2
FCH5030-680M	68.00	547.0	600.0	1.5	1.2

Remark:

<1>Inductance: 100KHz 0.1V

<2>Tolerance of inductance:±20%

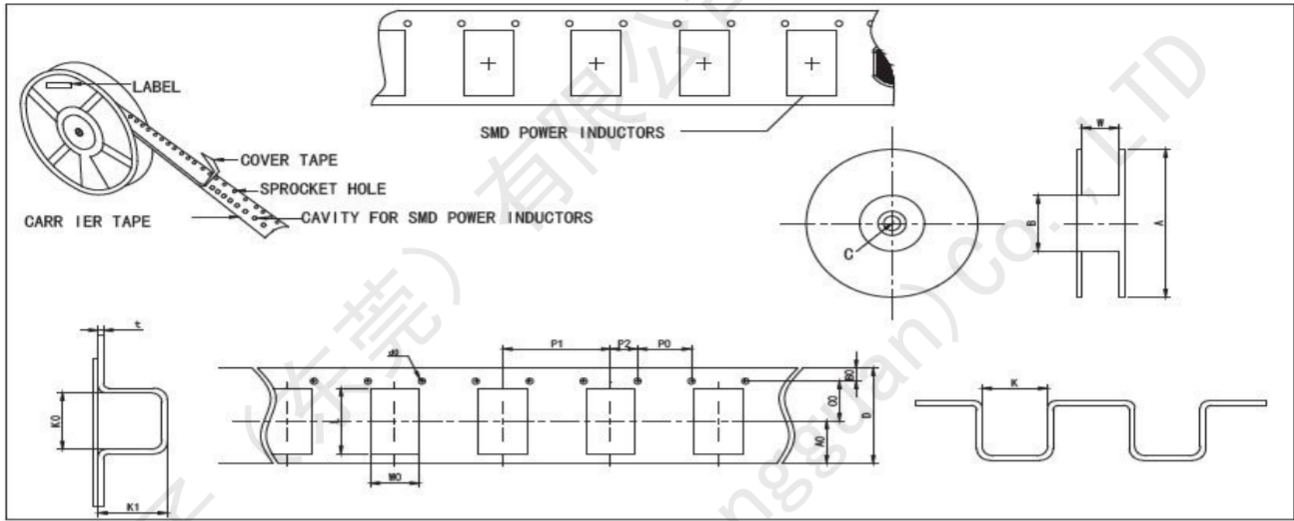
<3>Isat: The value of curret indicates that inductance drops 30%(Tycpial) from its initial value

<4>Irms:The value of current indicates that the temperature of the coil is increase 40°C (Typical)

<5>Test condition: Ta= 25°C

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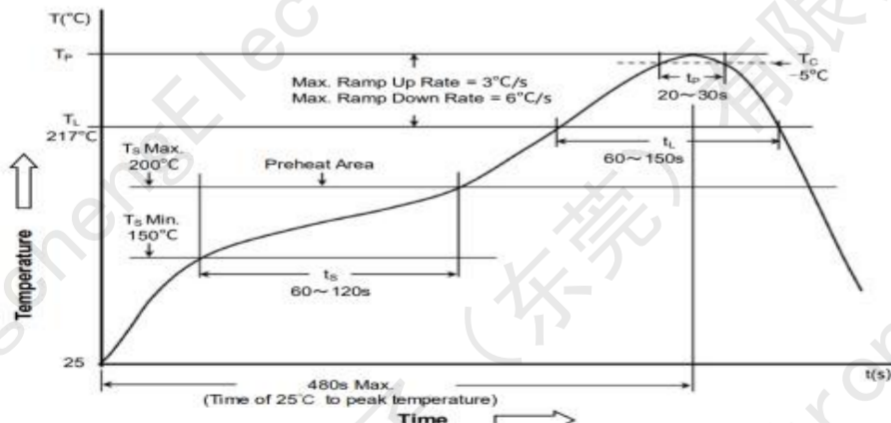
5.FCH5030-Series



●Reel Dimensions & Packing Unit(卷轴尺寸及包装数量)

Part Number 品名	Dimensions of Reel 卷轴尺寸				Packaging Unit 包装数
	A	B	C	W	
FCH5030	330	100.0±2.00	13.5±1.0	12.0±0.50	2000pcs/r

6. Reflow Profile for SMT Components



	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。